Product Change Notification

Change Notification #:	**116982 - 00**
Change Title:	**Select Intel® Platform Controller Hubs: FH82Q370, FH82CM246, FH82HM370, FH82QM370, FH82C246, FH82H310, PCN 116982-00, Manufacturing Site, Change the Assembly/Test site from Chengdu, China to Ho Chi Minh City, Vietnam.**
Date of Publication:	**June 12, 2019**

Key Characteristics of the Change:

Manufacturing Site

Forecasted Key Milestones:

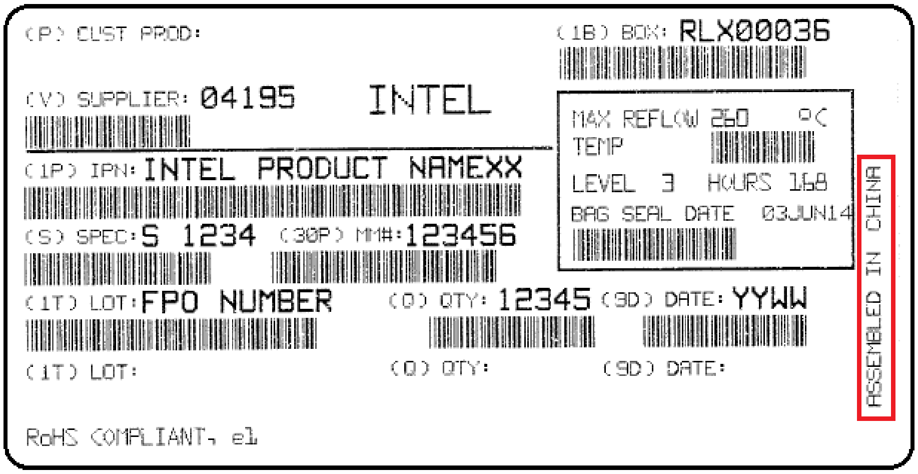
Date Customer Must be Ready to Receive Post-Conversion Material:	July 12, 2019

Description of Change to the Customer:

Intel will be changing the Assembly/Test site from Chengdu, People's Republic of China to an existing certified Manufacturing Site, Ho Chi Minh City, Vietnam to perform full flow manufacturing (Assembly, Test, and Finish) on the products listed in the Products Affected / Intel Ordering Codes table below.

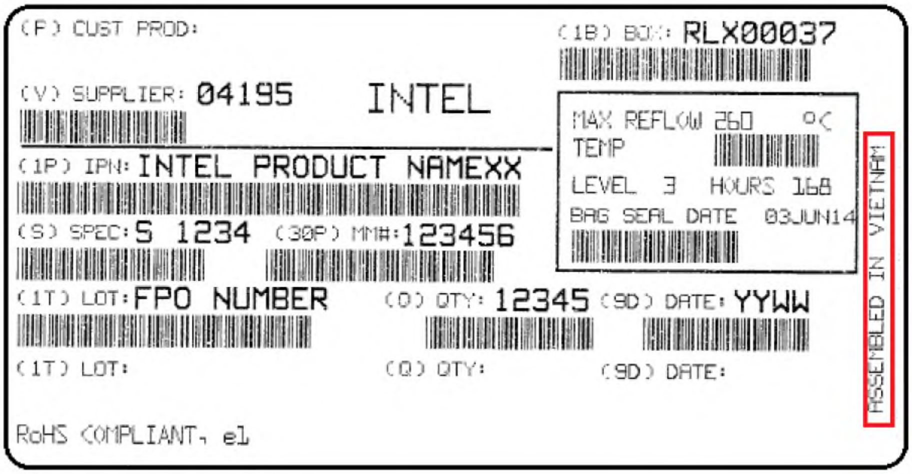
As a result, the COO (Country of Origin) mark will change on the box labels as shown in the images below. Additionally, the markings on device will change to reflect the change in COO. Devices originating from PRC contain a “V” prefix in the Finish Process Order (FPO) number marked on the device while those originating from Vietnam will contain an “X” prefix. The COO will also be printed on the Commercial Invoice which accompanies the shipment.

Current (Example only China as Country of Origin)



(P) CUST PROD:
(1B) BOX: RLX00036
(V) SUPPLIER: 04195 INTEL
MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14
(1P) IPN: INTEL PRODUCT NAMEXX
(S) SPEC: S 1234 (30P) MM#: 123456
(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW
(1T) LOT: (Q) QTY: (9D) DATE:
RoHS COMPLIANT, e1
ASSEMBLED IN CHINA

New (Example only Vietnam as Country of Origin)



(P) CUST PROD:
(1B) BOX: RLX00037
(V) SUPPLIER: 04195 INTEL
MAX REFLOW 260 °C
TEMP
LEVEL 3 HOURS 168
BAG SEAL DATE 03JUN14
(1P) IPN: INTEL PRODUCT NAMEXX
(S) SPEC: S 1234 (30P) MM#: 123456
(1T) LOT: FPO NUMBER (Q) QTY: 12345 (9D) DATE: YYWW
(1T) LOT: (Q) QTY: (9D) DATE:
RoHS COMPLIANT, e1
ASSEMBLED IN VIETNAM

Customer Impact of Change and Recommended Action:

The Assembly / Test site change has no impact on the form, fit, or function of these components. However, customers should notify their receiving department of the additional country involved in the manufacturing of the products impacted.

Customers may contact their Intel Field Sales Representative or the contacts listed on the last page of this Product Change Notification appropriate to your geo with questions.

Products Affected / Intel Ordering Codes:

Marketing Name	Stepping	Product Code	S-Spec	MM#
Intel® FH82Q370 Platform Controller Hub	B0	FH82Q370	S R404	964246
Intel® FH82C246 Platform Controller Hub	B0	FH82C246	S R40A	964268
Intel® FH82HM370 Platform Controller Hub	B0	FH82HM370	S R40B	964269
Intel® FH82QM370 Platform Controller Hub	B0	FH82QM370	S R40D	964271
Intel® FH82CM246 Platform Controller Hub	B0	FH82CM246	S R40E	964272
Intel® FH82H310 Platform Controller Hub	B0	FH82H310	S RCXY	978829

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
June 12, 2019	00	Originally Published PCN

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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